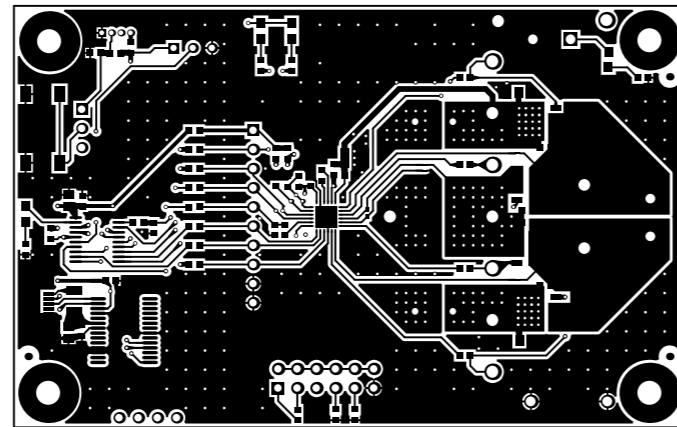
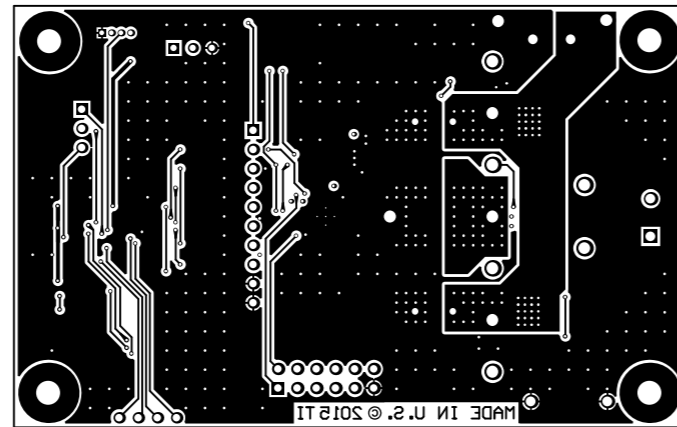


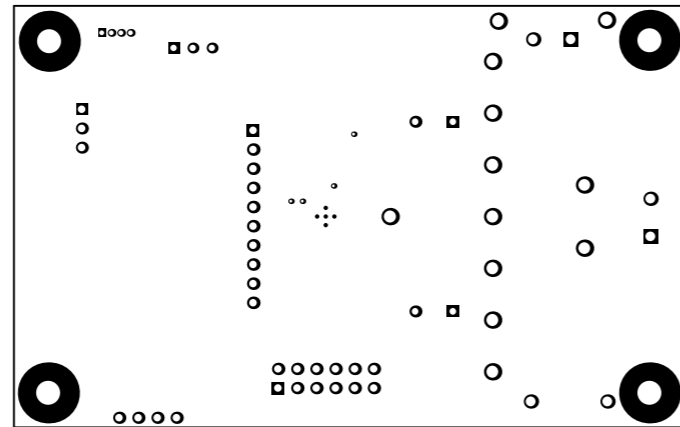
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/10/2015 5:36:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/10/2015 5:36:34 PM	TEXAS INSTRUMENTS	



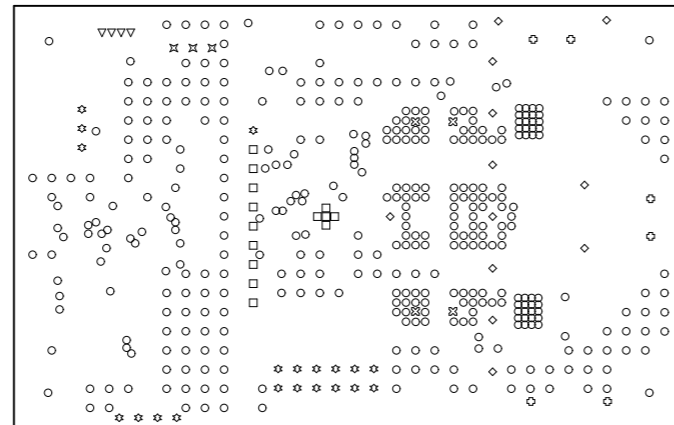
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/10/2015 5:36:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/10/2015 5:36:36 PM	TEXAS INSTRUMENTS	



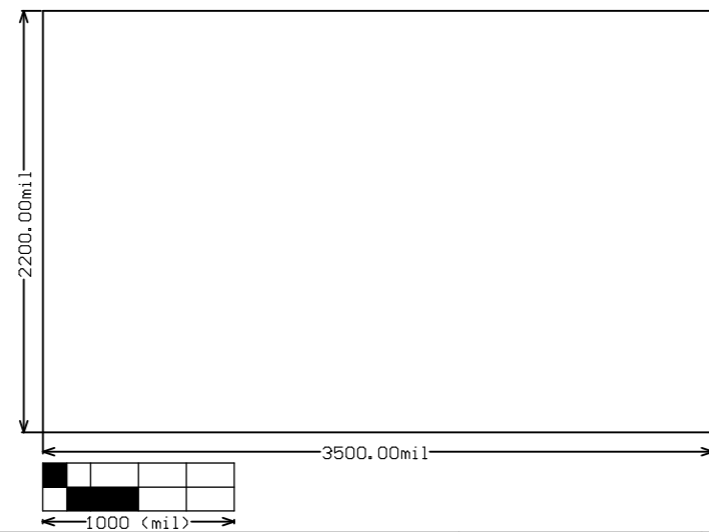
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EUM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 2/10/2015 5:36:36 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	5	8mil (0.203mm)	PTH	Round
○	396	15mil (0.381mm)	PTH	Round
▽	4	25.591mil (0.65mm)	PTH	Round
⊠	3	33.465mil (0.85mm)	PTH	Round
⊞	4	35.433mil (0.9mm)	PTH	Round
*	20	40mil (1.016mm)	PTH	Round
□	9	40.157mil (1.02mm)	PTH	Round
⊕	6	51.181mil (1.3mm)	PTH	Round
◇	12	63mil (1.6mm)	PTH	Round
○	4	125.984mil (3.2mm)	PTH	Round
463 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/10/2015 5:36:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DRV8701EVM	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/10/2015 5:36:37 PM	TEXAS INSTRUMENTS	

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